

DMP4050SSD

#### **40V DUAL P-CHANNEL ENHANCEMENT MODE MOSFET**

## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> Max	I <sub>D</sub> T <sub>A</sub> = +25°C
-40V	$50m\Omega$ @ $V_{GS} = -10V$	-5.2A
- <del>4</del> 0V	79mΩ @ V <sub>GS</sub> = -4.5V	-4.1A

### **Description**

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## **Applications**

- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

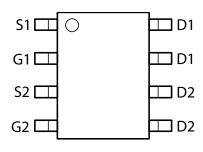
#### **Features and Benefits**

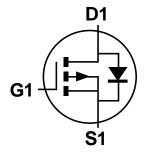
- Low On-Resistance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

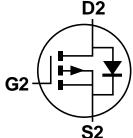
#### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (approximate)









Top View

Top View

**Equivalent Circuit** 

### **Ordering Information** (Note 4)

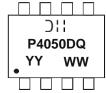
Part Number	Qualification	Case	Packaging
DMP4050SSD-13	Standard	SO-8	2500 / Tape & Reel
DMP4050SSDQ-13	Automotive	SO-8	2500 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

## **Marking Information**





DIII = Manufacturer's Marking
P4050SD = Product Type Marking Code for DMP4050SSD-13
P4050DQ = Product Type Marking Code for DMP4050SSDQ-13
YYWW = Date Code Marking
YY = Year (ex: 09 = 2009)
WW = Week (01-53)



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit V V
Drain-Source Voltage		V <sub>DSS</sub>	-40		
Gate-Source Voltage (Note 5)		V <sub>GS</sub>	±20		
		(Notes 9 & 11)		-5.2	
Continuous Drain Current V <sub>GS</sub> =	$V_{GS} = 10V$	T <sub>A</sub> = +70°C (Notes 7 & 9)	$I_{D}$	-4.2	Α
		(Notes 6 & 9)		-4.0	
Pulsed Drain Current	$V_{GS} = 10V$	(Notes 8 & 9)	I <sub>DM</sub>	-20.0	Α
Continuous Source Current (	Body Diode)	(Notes 7 & 9)	Is	-3.2	А
Pulsed Source Current (Body	y Diode)	(Notes 8 & 9)	I <sub>SM</sub>	-20.0	Α

# Thermal Characteristics ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

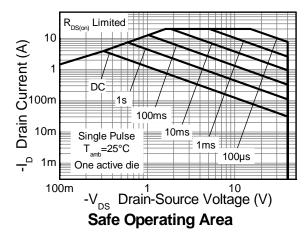
Characteristic		Symbol	Value	Unit	
	(Notes 6 & 9)		1.25 10.0		
Power dissipation Linear derating factor	(Notes 6 & 10)	P <sub>D</sub>	1.8 14.3	W mW/°C	
	(Notes 7 & 9)		2.14 17.2		
Thermal Resistance, Junction to Ambient	(Notes 6 & 9)		100		
	(Notes 6 & 10)	R <sub>0JA</sub>	70	00.044	
	(Notes 7 & 9)		58	°C/W	
Thermal Resistance, Junction to Lead	(Notes 9 & 11)	$R_{ heta JL}$	53		
Operating and storage temperature range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

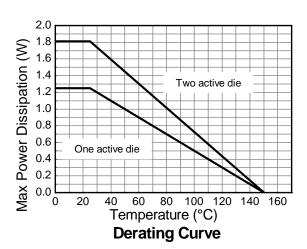
#### Notes:

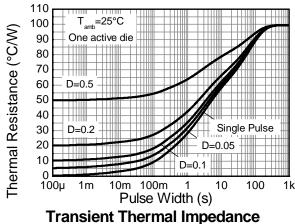
- 5. AEC-Q101 V<sub>SS</sub> maximum is ±16V.
  6. For a device surface mounted on 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 7. Same as note (3), except the device is measured at  $t \le 10$  sec.
- 8. Same as note (3), except the device is pulsed with D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.
- 9. For a dual device with one active die.
- 10. For a device with two active die running at equal power.
- 11. Thermal resistance from junction to solder-point (at the end of the drain lead).

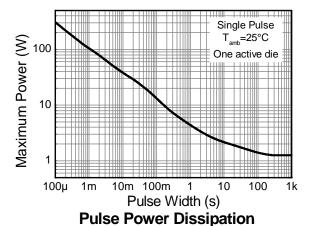


## **Thermal Characteristics**











## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

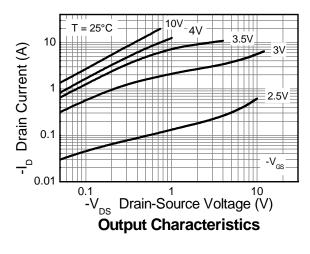
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-40	_	_	V	$I_D = -250 \mu A$ , $V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-0.5	μΑ	V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V <sub>GS(th)</sub>	-1.0	_	-3.0	V	$I_D = -250\mu A,\ V_{DS} = V_{GS}$	
Static Drain-Source On-Resistance (Note 12)	В		0.038	0.050	Ω	$V_{GS} = -10V, I_D = -6A$	
Static Dialii-Source Off-Resistance (Note 12)	R <sub>DS(ON)</sub>	_	0.055	0.079	22	$V_{GS} = -4.5V, I_{D} = -5A$	
Forward Transconductance (Notes 12 & 13)	g <sub>fs</sub>	_	14	_	S	V <sub>DS</sub> = -15V, I <sub>D</sub> = -6A	
Diode Forward Voltage (Note 12)	V <sub>SD</sub>	_	-0.86	-1.2	V	I <sub>S</sub> = -6A, V <sub>GS</sub> = 0V	
Reverse recovery time (Note 13)	t <sub>rr</sub>		18	_	ns	I <sub>S</sub> = -2A, di/dt = 100A/μs	
Reverse recovery charge (Note 13)	Qrr	_	12.7	_	nC		
DYNAMIC CHARACTERISTICS (Note 13)							
Input Capacitance	C <sub>iss</sub>	_	674	_	pF	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V f = 1MHz	
Output Capacitance	Coss	_	115	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	67.7	_	pF	1 - 1141112	
Total Gate Charge (Note 14)	Qg	_	6.9	_	nC	V <sub>GS</sub> = -4.5V	
Total Gate Charge (Note 14)	Qg	_	13.9	_	nC	V <sub>DS</sub> = -20V	
Gate-Source Charge (Note 14)	$Q_{gs}$	_	2	_	nC	$V_{GS} = -10V$ $I_D = -6A$	
Gate-Drain Charge (Note 14)	Q <sub>gd</sub>	_	3.4	_	nC	1	
Turn-On Delay Time (Note 14)	t <sub>D(on)</sub>	_	1.9	_	ns	·	
Turn-On Rise Time (Note 14)	t <sub>r</sub>	_	3.1	_	ns	$V_{DD} = -20V, V_{GS} = -10V$ $I_{D} = -1A, R_{G} \approx 6.0\Omega$	
Turn-Off Delay Time (Note 14)	t <sub>D(off)</sub>	_	31.5	_	ns		
Turn-Off Fall Time (Note 14)	t <sub>f</sub>	_	12.6	_	ns		

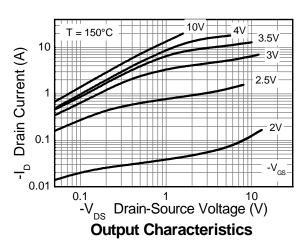
Notes:

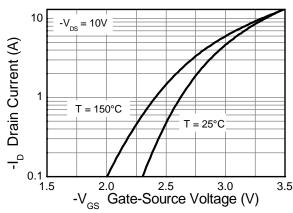
<sup>12.</sup> Measured under pulsed conditions. Pulse width  $\leq 300 \mu s$ ; duty cycle  $\leq 2\%$  13. For design aid only, not subject to production testing. 14. Switching characteristics are independent of operating junction temperatures.

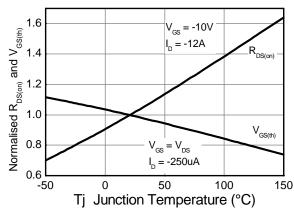


## **Typical Characteristics**



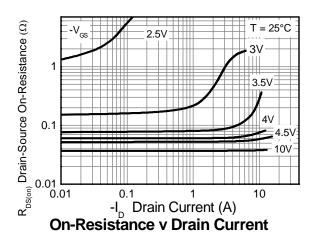


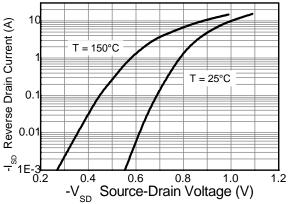




**Typical Transfer Characteristics** 

**Normalised Curves v Temperature** 

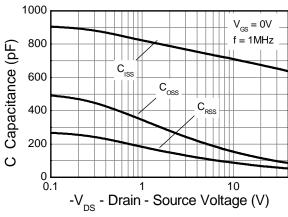




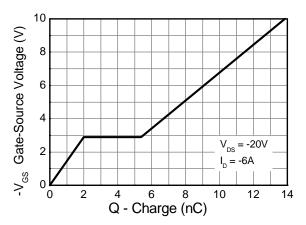
**Source-Drain Diode Forward Voltage** 



## **Typical Characteristics – (cont.)**

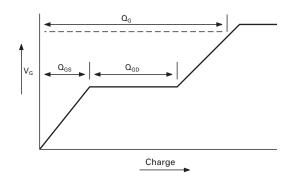


Capacitance v Drain-Source Voltage

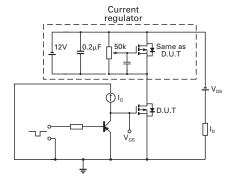


Gate-Source Voltage v Gate Charge

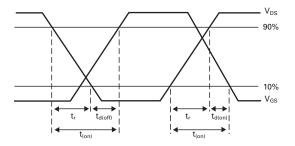
## **Test Circuits**



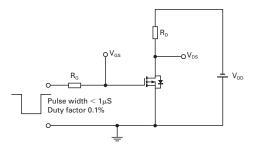
Basic gate charge waveform



Gate charge test circuit



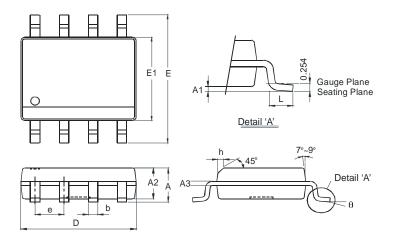
Switching time waveforms



Switching time test circuit

# **Package Outline Dimensions**

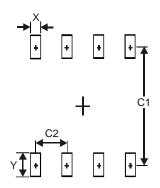
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SO-8					
Dim	Min	Max			
Α	-	1.75			
A1	0.10	0.20			
A2	1.30	1.50			
A3	0.15	0.25			
b	0.3	0.5			
D	4.85	4.95			
Е	5.90	6.10			
E1	3.85	3.95			
е	1.27 Typ				
h	-	0.35			
L	0.62	0.82			
θ	0°	8°			
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.60
Υ	1.55
C1	5.4
C2	1.27





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